

**Die Bonder**

**Manufacturer:** finetech

**Model:** FINEPLACER lambda



**General Description:**

The FINEPLACER lambda is a flexible sub- micron bonder used for precise placement, die attach and advanced packaging. The system offers outstanding flexibility with a modular design and can be easily reconfigured for different applications.

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**Key Specifications:**

- Sub- micron placement accuracy
- Handles ultra-small components, special tools allow object sizes > 5 µm
- Supported substrate size up to 6"
- Small footprint and compact design

**Availability:**

Use allowed for all researchers with permission

**Location**

Clean room  
 Europastraße 12  
 9524 Villach

**Responsibles / Contact**

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